Device Material Content

5555 NE Moore Ct.
Hillsboro OR 97124
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Package: 32 QFN with matte Sn Plating

Total Device Weight 0.06 Grams

August, 2005	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	Notes / Assumptions:
Die	4.59%	0.003			Silicon	7440-21-3	Die size: 2.10 x 2.15 mm
Mold	46.18%	0.027					Mold Compound Density between 1.7 and 2.1 grams/cc
			39.14%	0.023	Silica Fused	60676-86-0	75 to 95% Fused Silica (LSC uses 84.75% in our calculation)
			3.46%	0.0020	Epoxy Resin	129915-35-1	5 to 10% Epoxy Resin (LSC uses 7.5% in our calculation)
			3.46%	0.0020	Phenol Resin	26834-02-6	5 to 10% Phenol Resin (LSC uses 7.5% in our calculation)
			0.12%	0.0001	Carbon Black	1333-86-4	0.1 to 0.5% Carbon Black (LSC uses 0.25% in our calculation)
D/A Epoxy	0.79%	0.0005			Silver filled epoxy	7440-22-4	Die attach epoxy Density: 4 grams/cc (silver content: 60-100%)
Wire	0.81%	0.0005			Gold (Au)	7440-57-5	1.00 mil diameter; 1 wire per package lead; wire length 1.5 mm
Lead Plating	1.98%	0.0012			Tin (Sn)	7440-31-5	Plating is 100%; thickness is 0.015mm
Leadframe	45.65%	0.027					Leadframe thickness is nominal (per Case Outline)
			44.48%	0.026	Copper (Cu)	7440-50-8	96 to 99% Cu (LSC uses 97.45% in our calculation)
			1.10%	0.0006	Iron (Fe)	7439-89-6	2 to 2.8% Fe (LSC uses 2.4% in our calculation)
			0.05%	0.00003	Zinc (Zn)	7440-66-6	0.08 to 0.16% Zn (LSC uses 0.12% in our calculation)
			0.01%	0.00001	Phosphorus (P)	7723-14-0	0.01 to 0.05% P (LSC uses 0.03% in our calculation)

Notes:

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.

Constituent substances and proportions in epoxy materials are before curing.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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